

## Description

The μPD424256 is a fast-page dynamic RAM organized as 262,144 words by 4 bits and designed to operate from a single +5-volt power supply. Advanced polycide technology using trench capacitors minimizes silicon area and provides high storage cell capacity, high performance, and high reliability. A single-transistor dynamic storage cell and advanced CMOS circuitry throughout ensure minimum power dissipation, while an on-chip circuit generates the negative-voltage substrate bias automatically and transparently.

The three-state I/O pins are controlled by  $\overline{\text{CAS}}$  independent of  $\overline{\text{RAS}}$ . After a valid read or read-modify-write cycle, data is held on the outputs by maintaining  $\overline{\text{CAS}}$  low. The data outputs are returned to high impedance by returning  $\overline{\text{CAS}}$  high. Fast-page read and write cycles can be executed by cycling  $\overline{\text{CAS}}$ .

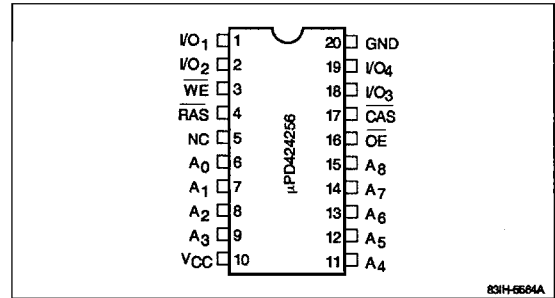
Refreshing may be accomplished by means of a  $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  cycle whereby the refresh addresses are internally generated. Refreshing may also be accomplished by means of  $\overline{\text{RAS}}$ -only refresh cycles or by normal read or write cycles on the 512 address combinations of  $A_0$  through  $A_8$  during an 8-ms refresh period (64 ms for -L versions).

## Features

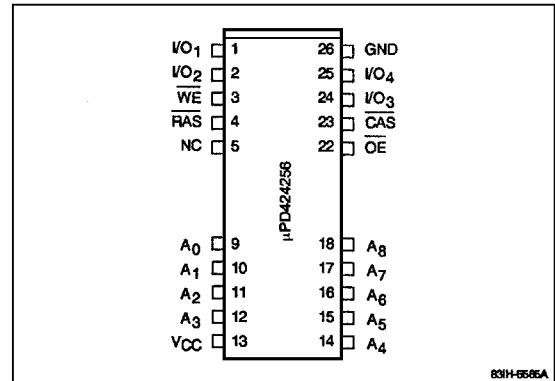
- 262,144-word by 4-bit organization
- Single +5-volt power supply
- Fast-page option
- Low power available in -L version
- $\overline{\text{CAS}}$  before  $\overline{\text{RAS}}$  internal refreshing
- Multiplexed address inputs
- On-chip substrate bias generator
- Nonlatched, three-state I/O
- TTL-compatible inputs and outputs
- High-density 20-pin DIP, 26/20-pin SOJ, 20-pin ZIP, or 24/20-pin TSOP plastic packaging

## Pin Configurations

### 20-Pin Plastic DIP

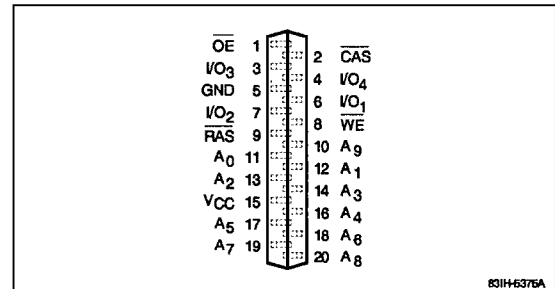


### 26/20-Pin Plastic SOJ



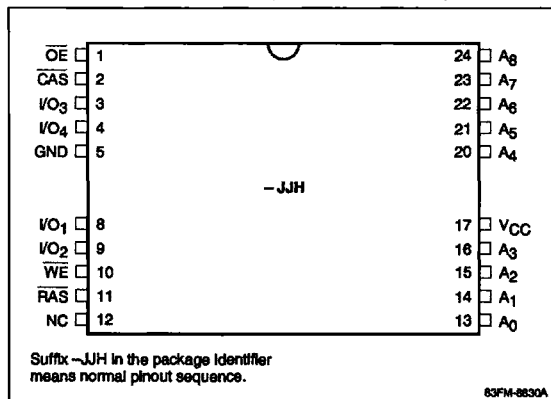
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### 20-Pin Plastic ZIP

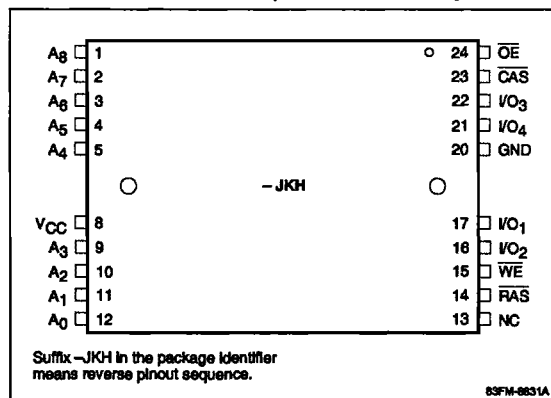


Pin Configurations (cont)

24/20-Pin Plastic TSOP (Normal Pinouts)



24/20-Pin Plastic TSOP (Reverse Pinouts)



Pin Identification

Name	Function
A <sub>0</sub> - A <sub>8</sub>	Address inputs
I/O <sub>1</sub> - I/O <sub>4</sub>	Data inputs and outputs
CAS	Column address strobe
OE	Output enable
RAS	Row address strobe
WE	Write enable
GND	Ground
V <sub>CC</sub>	+ 5-volt power supply
NC	No connection

Absolute Maximum Ratings

Voltage on any pin relative to GND	-1.0 to +7.0 V
Operating temperature, T <sub>OPR</sub>	0 to +70°C
Storage temperature, T <sub>STG</sub>	-55 to +125°C
Short-circuit output current, I <sub>OS</sub>	50 mA
Power dissipation, P <sub>D</sub>	1.0 W

Exposure to Absolute Maximum Ratings for extended periods may affect device reliability; exceeding the ratings could cause permanent damage. The device should be operated within the limits specified under DC and AC Characteristics.

Recommended Operating Conditions

Parameter	Symbol	Min	Typ	Max	Unit
Input voltage, high	V <sub>IH</sub>	2.4		V <sub>CC</sub> + 1.0	V
Input voltage, low	V <sub>IL</sub>	-1.0		0.8	V
Supply voltage	V <sub>CC</sub>	4.5	5.0	5.5	V
Ambient temperature	T <sub>A</sub>	0		70	°C

Capacitance

T<sub>A</sub> = 25°C; f = 1 MHz

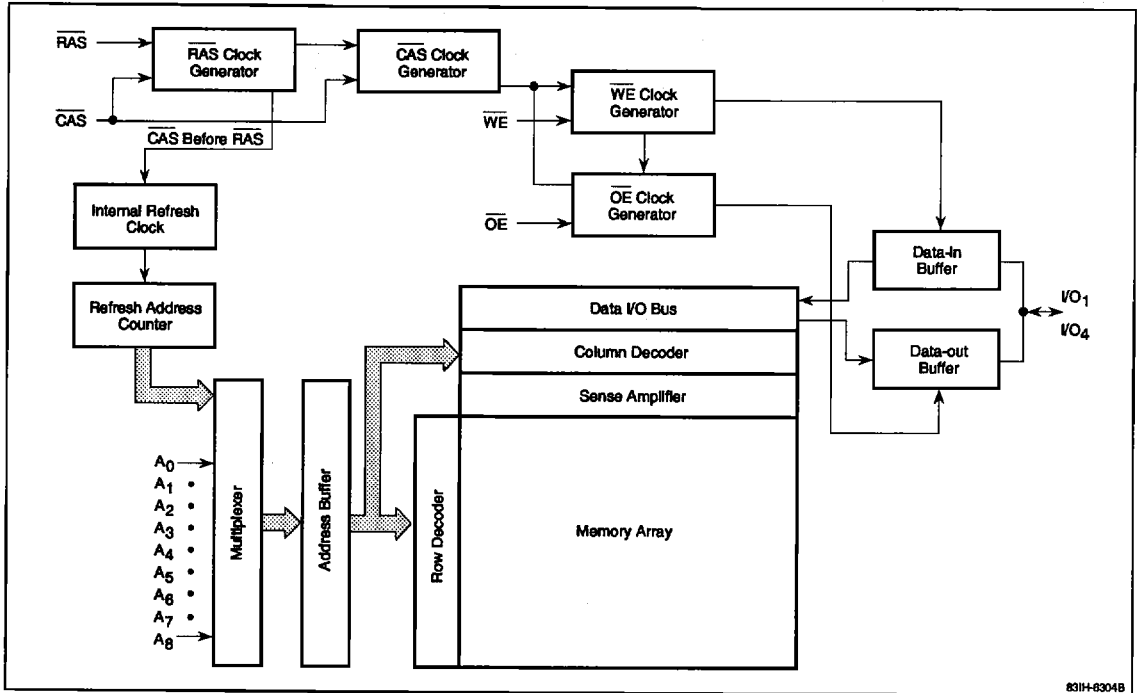
Parameter	Symbol	Max	Unit	Pins Under Test
Input capacitance	C <sub>I1</sub>	5	pF	Address
	C <sub>I2</sub>	7	pF	RAS, CAS, WE, OE
Input/output capacitance	C <sub>IO</sub>	7	pF	I/O

### Ordering Information

Part Number	RAS Access Time (max)	R/W Cycle Time (max)	Fast-Page Cycle (max)	Refresh Period	Standby Current (min)	Package
μPD424256C-60	60 ns	120 ns	40 ns	8 ms	1 mA	20-pin plastic DIP
C-70	70 ns	130 ns	45 ns			
C-80	80 ns	160 ns	50 ns			
C-10	100 ns	190 ns	60 ns			
μPD424256C-60L	60 ns	120 ns	40 ns	64 ms	200 μA	
C-70L	70 ns	130 ns	45 ns			
C-80L	80 ns	160 ns	50 ns			
C-10L	100 ns	190 ns	60 ns			
μPD424256LA-60	60 ns	120 ns	40 ns	8 ms	1 mA	26/20-pin plastic SOJ
LA-70	70 ns	130 ns	45 ns			
LA-80	80 ns	160 ns	50 ns			
LA-10	100 ns	190 ns	60 ns			
μPD424256LA-60L	60 ns	120 ns	40 ns	64 ms	200 μA	
LA-70L	70 ns	130 ns	45 ns			
LA-80L	80 ns	160 ns	50 ns			
LA-10L	100 ns	190 ns	60 ns			
μPD424256V-60	60 ns	120 ns	40 ns	8 ms	1 mA	20-pin plastic ZIP
V-70	70 ns	130 ns	45 ns			
V-80	80 ns	160 ns	50 ns			
V-10	100 ns	190 ns	60 ns			
μPD424256V-60L	60 ns	120 ns	40 ns	64 ms	200 μA	
V-70L	70 ns	130 ns	45 ns			
V-80L	80 ns	160 ns	50 ns			
V-10L	100 ns	190 ns	60 ns			
μPD424256GX-60	60 ns	120 ns	40 ns	8 ms	1 mA	24/20-pin plastic TSOP (normal leads)
GX-70	70 ns	130 ns	45 ns			
GX-80	80 ns	160 ns	50 ns			
GX-10	100 ns	190 ns	60 ns			
μPD424256GX-60L	60 ns	120 ns	40 ns	64 ms	200 μA	
GX-70L	70 ns	130 ns	45 ns			
GX-80L	80 ns	160 ns	50 ns			
GX-10L	100 ns	190 ns	60 ns			
μPD424256GXM-60	60 ns	120 ns	40 ns	8 ms	1 mA	24/20-pin plastic TSOP (reverse bent leads)
GXM-70	70 ns	130 ns	45 ns			
GXM-80	80 ns	160 ns	50 ns			
GXM-10	100 ns	190 ns	60 ns			
μPD424256GXM-60L	60 ns	120 ns	40 ns	64 ms	200 μA	
GXM-70L	70 ns	130 ns	45 ns			
GXM-80L	80 ns	160 ns	50 ns			
GXM-10L	100 ns	190 ns	60 ns			

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Block Diagram



831H-6304B

DC Characteristics

T<sub>A</sub> = 0 to +70°C; V<sub>CC</sub> = +5.0 V ±10%

Parameter	Symbol	Min	Typ	Max	Unit	Test Conditions
Standby current	I <sub>CC2</sub>			2.0	mA	RAS = CAS = V <sub>IH</sub>
				1.0	mA	RAS = CAS ≥ V <sub>CC</sub> - 0.2 V
Input leakage current	I <sub>I(L)</sub>	-10		10	μA	V <sub>IN</sub> = 0 to 5.5 V; all other pins not under test = 0 V
Output leakage current	I <sub>O(L)</sub>	-10		10	μA	D <sub>OUT</sub> disabled; V <sub>OUT</sub> = 0 to 5.5 V
Output voltage, low	V <sub>OL</sub>			0.4	V	I <sub>OL</sub> = 4.2 mA
Output voltage, high	V <sub>OH</sub>	2.4			V	I <sub>OH</sub> = -5 mA

## AC Characteristics

$T_A = 0$  to  $+70$  °C;  $V_{CC} = +5.0V \pm 10\%$

Parameter	Symbol	-60		-70		-80		-10		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max	Min	Max		
Operating current, average	$I_{CC1}$		90		80		70		60	mA	$\overline{RAS}$ and $\overline{CAS}$ cycling; $t_{RC} = t_{RC}$ min; (Note 5)
Operating current, RAS-only refresh cycle, average	$I_{CC3}$		90		80		70		60	mA	RAS cycling; $\overline{CAS} = V_{IH}$ ; $t_{RC} = t_{RC}$ min; (Note 5)
Operating current, fast-page cycle, average	$I_{CC4}$		80		70		60		50	mA	$\overline{RAS} = V_{IL}$ ; $\overline{CAS}$ cycling; $t_{PC} = t_{PC}$ min; (Note 5)
Operating current, CAS before RAS refresh cycle, average	$I_{CC5}$		90		80		70		60	mA	RAS cycling; $\overline{CAS} = V_{IL}$ ; $t_{RC} = t_{RC}$ min; (Note 5)
Access time from column address	$t_{AA}$		30		35		45		50	ns	(Notes 7, 10, 13)
Access time from $\overline{CAS}$ precharge (rising edge)	$t_{ACP}$		35		40		45		55	ns	(Notes 7, 13)
Column address hold time referenced to RAS	$t_{AR}$	N/A		N/A		60		70		ns	
Column address setup time	$t_{ASC}$	0		0		0	20	0	20	ns	(Note 13)
Row address setup time	$t_{ASR}$	0		0		0		0		ns	
Column address to $\overline{WE}$ delay time	$t_{AWD}$	50		55		70		80		ns	(Note 18)
Access time from $\overline{CAS}$ (falling edge)	$t_{CAC}$		20		20		20		25	ns	(Notes 7, 9, 10, 13)
Column address hold time	$t_{CAH}$	15		17		20		20		ns	
$\overline{CAS}$ pulse width	$t_{CAS}$	20	10,000	20	10,000	20	10,000	25	10,000	ns	
$\overline{CAS}$ hold time for CAS before RAS refresh cycle	$t_{CHR}$	15		15		15		20		ns	
$\overline{CAS}$ precharge time, fast-page cycle	$t_{CP}$	10		10	15	10	20	10	25	ns	(Note 13)
$\overline{CAS}$ precharge time, nonpage cycle	$t_{CPN}$	10		10		10		10		ns	
$\overline{CAS}$ to RAS precharge time	$t_{CRP}$	10		10		10		10		ns	(Note 14)
$\overline{CAS}$ hold time	$t_{CSH}$	60		70		80		100		ns	
$\overline{CAS}$ setup time for CAS before RAS refresh cycle	$t_{CSR}$	10		10		10		10		ns	
$\overline{CAS}$ to $\overline{WE}$ delay	$t_{CWD}$	40		40		45		55		ns	(Note 18)
Write command to CAS lead time	$t_{CWL}$	15		15		20		20		ns	
Data-in hold time	$t_{DH}$	15		15		20		20		ns	(Note 17)

AC Characteristics (cont)

Parameter	Symbol	-60		-70		-80		-10		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max	Min	Max		
Data-in hold time referenced to $\overline{\text{RAS}}$	$t_{\text{DHR}}$	N/A		N/A		60		70		ns	
Data-in setup time	$t_{\text{DS}}$	0		0		0		0		ns	(Note 17)
Access time from $\overline{\text{OE}}$	$t_{\text{OEA}}$	20		20		20		25		ns	
$\overline{\text{OE}}$ data delay time	$t_{\text{OED}}$	15		15		20		25		ns	
$\overline{\text{OE}}$ command hold time	$t_{\text{OEH}}$	0		0		0		0		ns	
$\overline{\text{OE}}$ to $\overline{\text{RAS}}$ inactive setup time	$t_{\text{OES}}$	0		0		0		0		ns	
Output turnoff delay from $\overline{\text{OE}}$	$t_{\text{OEZ}}$	0	15	0	15	0	20	0	25	ns	(Note 11)
Output buffer turnoff delay	$t_{\text{OFF}}$	0	15	0	15	0	20	0	25	ns	(Note 11)
Fast-page cycle time	$t_{\text{PC}}$	40		45		50		60		ns	(Note 6)
Fast-page read-write cycle time	$t_{\text{PRWC}}$	85		90		105		125		ns	
Access time from $\overline{\text{RAS}}$	$t_{\text{RAC}}$	60		70		80		100		ns	(Notes 7, 8)
$\overline{\text{RAS}}$ to column address delay time	$t_{\text{RAD}}$	15	30	15	35	17	35	17	50	ns	(Note 10)
Row address hold time	$t_{\text{RAH}}$	10		10		12		12		ns	
Column address lead time referenced to $\overline{\text{RAS}}$ (rising edge)	$t_{\text{RAL}}$	30		35		45		50		ns	
$\overline{\text{RAS}}$ pulse width	$t_{\text{RAS}}$	60	10,000	70	10,000	80	10,000	100	10,000	ns	
$\overline{\text{RAS}}$ pulse width, fast-page cycle	$t_{\text{RASp}}$	60	100,000	70	100,000	80	100,000	100	100,000	ns	
Random read or write cycle time	$t_{\text{RC}}$	120		130		160		190		ns	(Note 6)
$\overline{\text{RAS}}$ to $\overline{\text{CAS}}$ delay time	$t_{\text{RCD}}$	20	40	20	50	25	60	25	75	ns	(Note 12)
Read command hold time referenced to $\overline{\text{CAS}}$	$t_{\text{RCH}}$	0		0		0		0		ns	(Note 15)
Read command setup time	$t_{\text{RCS}}$	0		0		0		0		ns	
Refresh period	$t_{\text{REF}}$	8		8		8		8		ms	Addresses $A_0 - A_8$ ; 64 ms for -L versions
$\overline{\text{RAS}}$ precharge time	$t_{\text{RP}}$	50		50		70		80		ns	
$\overline{\text{RAS}}$ precharge $\overline{\text{CAS}}$ hold time	$t_{\text{RPC}}$	10		10		10		10		ns	
Read command hold time referenced to $\overline{\text{RAS}}$	$t_{\text{RRH}}$	10		10		10		10		ns	(Note 15)
$\overline{\text{RAS}}$ hold time	$t_{\text{RSH}}$	20		20		20		25		ns	
Read-write cycle time	$t_{\text{RWC}}$	165		175		215		255		ns	(Note 6)
$\overline{\text{RAS}}$ to $\overline{\text{WE}}$ delay	$t_{\text{RWD}}$	80		90		105		130		ns	(Note 18)

## AC Characteristics (cont)

Parameter	Symbol	-60		-70		-80		-10		Unit	Test Conditions
		Min	Max	Min	Max	Min	Max	Min	Max		
Write command to RAS lead time	$t_{RWL}$	20		20		25		30		ns	
Rise and fall transition time	$t_T$	3	50	3	50	3	50	3	50	ns	(Note 4)
Write command hold time	$t_{WCH}$	15		15		15		20		ns	
Write command hold time referenced to RAS	$t_{WCR}$	N/A		N/A		55		70		ns	
Write command setup time	$t_{WCS}$	0		0		0		0		ns	(Note 18)
Write command pulse width	$t_{Wp}$	15		15		15		20		ns	(Note 18)

### Notes:

- (1) All voltages are referenced to GND.
- (2) An initial pause of 100 μs is required after power-up, followed by any eight RAS cycles, before proper device operation is achieved.
- (3) Ac measurements assume  $t_T = 5$  ns.
- (4)  $V_{IH}$  (min) and  $V_{IL}$  (max) are reference levels for measuring the timing of input signals. Transition times are measured between  $V_{IH}$  and  $V_{IL}$ .
- (5)  $I_{CC1}$ ,  $I_{CC3}$ ,  $I_{CC4}$ , and  $I_{CC5}$  depend on output loading and cycle rates. Specified values are obtained with the output open.  $I_{CC3}$  is measured assuming that all column address inputs are held at either a high level or a low level during RAS-only refresh cycles.  $I_{CC4}$  is measured assuming that all column address inputs are switched only once during each fast-page cycle.
- (6) The minimum specifications are used only to indicate the cycle time at which proper operation over the full temperature range ( $T_A = 0$  to  $+70^\circ\text{C}$ ) is assured.
- (7) Load = 2 TTL ( $-1$  mA,  $+4$  mA) loads and 100 pF.
- (8) Assumes that  $t_{RCD} \leq t_{RCD}(\text{max})$  and  $t_{RAD} \leq t_{RAD}(\text{max})$ . If  $t_{RCD}$  or  $t_{RAD}$  is greater than the maximum recommended value in this table,  $t_{RAC}$  increases by the amount that  $t_{RCD}$  or  $t_{RAD}$  exceeds the value shown.
- (9) Assumes that  $t_{RCD} \geq t_{RCD}(\text{max})$  and  $t_{RAD} \leq t_{RAD}(\text{max})$ .
- (10) If  $t_{RAD} \geq t_{RAD}(\text{max})$ , then the access time is defined by  $t_{AA}$ .
- (11)  $t_{OFF}(\text{max})$  and  $t_{OEZ}(\text{max})$  define the time at which the outputs achieve the open-circuit condition and are not referenced to  $V_{OH}$  or  $V_{OL}$ .
- (12) Operation with the  $t_{RCD}(\text{max})$  limit assures that  $t_{RAC}(\text{max})$  can be met.  $t_{RCD}(\text{max})$  is specified as a reference point only; if  $t_{RCD}$  is greater than  $t_{RCD}(\text{max})$ , access time is controlled exclusively by  $t_{CAC}$ .

- (13) For fast-page read operation, the definition of access time is as follows:

CAS and Column Address Input Conditions	Access Time Definition
$t_{CP} \leq t_{CP}(\text{max}), t_{ASC} \geq t_{CP}$	$t_{ACP}$
$t_{CP} \leq t_{CP}(\text{max}), t_{ASC} \leq t_{CP}$	$t_{AA}$
$t_{CP} \geq t_{CP}(\text{max}), t_{ASC} \leq t_{ASC}(\text{max})$	$t_{AA}$
$t_{CP} \geq t_{CP}(\text{max}), t_{ASC} \geq t_{ASC}(\text{max})$	$t_{CAC}$

- (14) The  $t_{CRP}$  requirement should be applicable for  $\overline{\text{RAS}}/\overline{\text{CAS}}$  cycles preceded by any cycle.
- (15) Either  $t_{RRH}$  or  $t_{RCH}$  must be satisfied for a read cycle.
- (16) Parameter  $t_{WP}$  is applicable for a delayed write cycle such as a read-write/read-modify-write cycle. For early write cycles, both  $t_{WCS}$  and  $t_{WCH}$  must be met.
- (17) These parameters are referenced to the falling edge of  $\overline{\text{CAS}}$  for early write cycles and to the falling edge of  $\overline{\text{WE}}$  for delayed write or read-modify-write cycles.
- (18)  $t_{WCS}$ ,  $t_{RWD}$ ,  $t_{CWD}$ , and  $t_{AWD}$  are restrictive operating parameters in read-write/read-modify-write cycles only. If  $t_{WCS} \geq t_{WCS}(\text{min})$ , the cycle is an early write cycle and the data I/O pins will remain open-circuit throughout the entire cycle. If  $t_{CWD} \geq t_{CWD}(\text{min})$ ,  $t_{RWD} \geq t_{RWD}(\text{min})$ , and  $t_{AWD} \geq t_{AWD}(\text{min})$ , then the cycle is a read-write cycle and the data I/O pins will contain data read from the selected cells. If neither of the above conditions is met, the condition of the data I/O pins (at access time and until CAS returns to  $V_{IH}$ ) is indeterminate.

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**Low Power Battery Backup (-L Versions Only)**

The μPD424256-L is capable of low power battery backup during times of reduced system power, when the input buffers and all nonessential internal circuits are turned off. For the input buffers to be turned off and the amount of leakage current flowing through them reduced, the μPD424256-L must be in standby and all control lines within 0.2 V of either  $V_{CC}$  or GND, as appropriate. When  $\overline{RAS}$  and  $\overline{CAS}$  are both within 0.2 V of  $V_{CC}$ , the internal circuits are inactive and power requirements reduced even further. Standby current can drop as low as 200 μA.

$\overline{CAS}$  before  $\overline{RAS}$  refresh cycles are executed at a minimum rate to ensure that all 512 rows are refreshed only once every 64 ms. The time that  $\overline{RAS}$  is low ( $t_{RAS}$ ) and the μPD424256-L active needs to be as short as possible, typically less than 300 ns, to minimize power usage during refresh operation. The following table shows the conditions under which the lowest average standby current can be obtained.

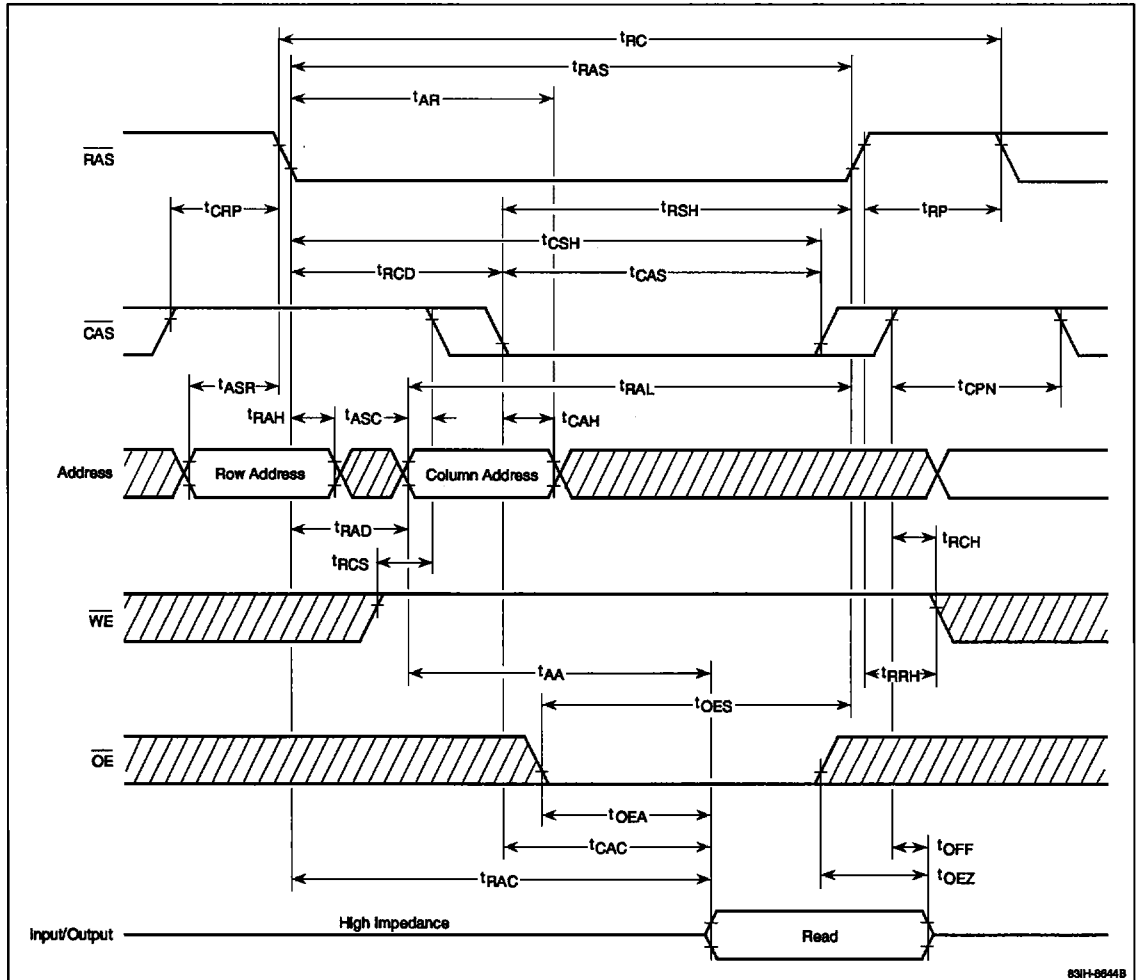
**Battery Backup Current**

Symbol	Max	Unit	CAS Before RAS Refresh Cycle	Standby Conditions
$I_{CC6}$	200	μA	$t_{RAS} \leq 300 \text{ ns}$	$\overline{RAS} = \overline{CAS} \geq V_{CC} - 0.2 \text{ V}$ ; $\overline{OE} \geq V_{CC} - 0.2 \text{ V}$ ; $\overline{WE} = \text{Addresses} \geq V_{CC} - 0.2 \text{ V}$ or $\leq 0.2 \text{ V}$ ; I/O $\geq V_{CC} - 0.2 \text{ V}$ or $\leq 0.2 \text{ V}$ or high-Z
$I_{CC6}$	300	μA	$t_{RAS} \geq 300 \text{ ns}$ and $\leq 1 \mu\text{s}$	



## Timing Waveforms

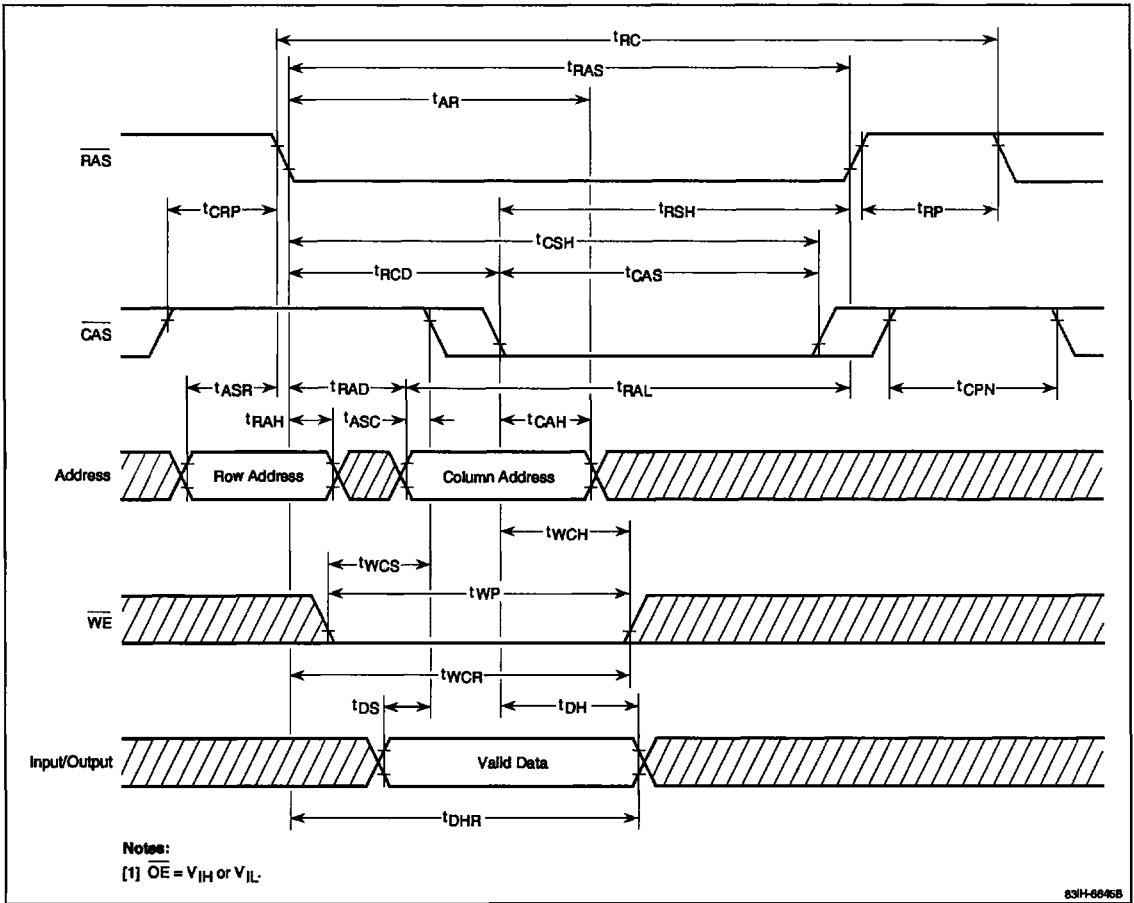
### Read Cycle



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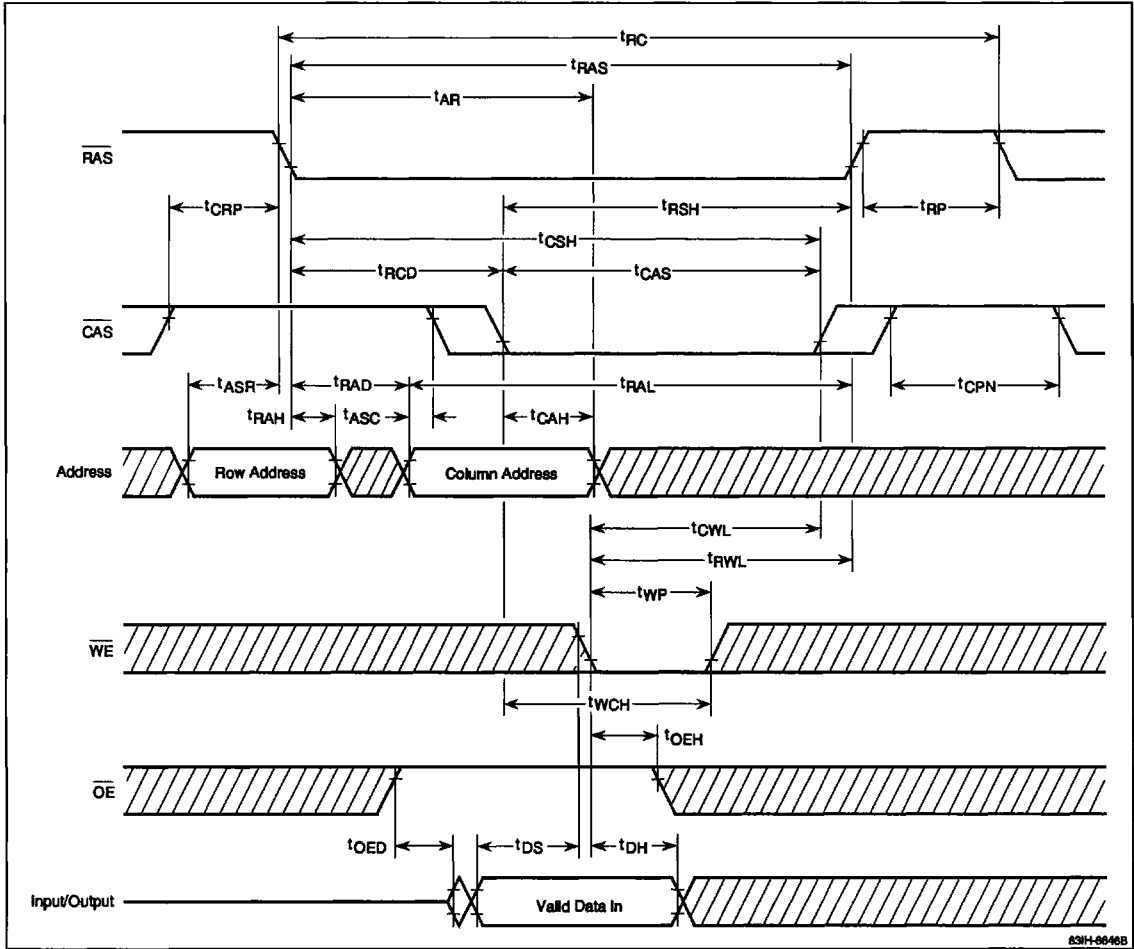
Timing Waveforms (cont)

Early Write Cycle



## Timing Waveforms (cont)

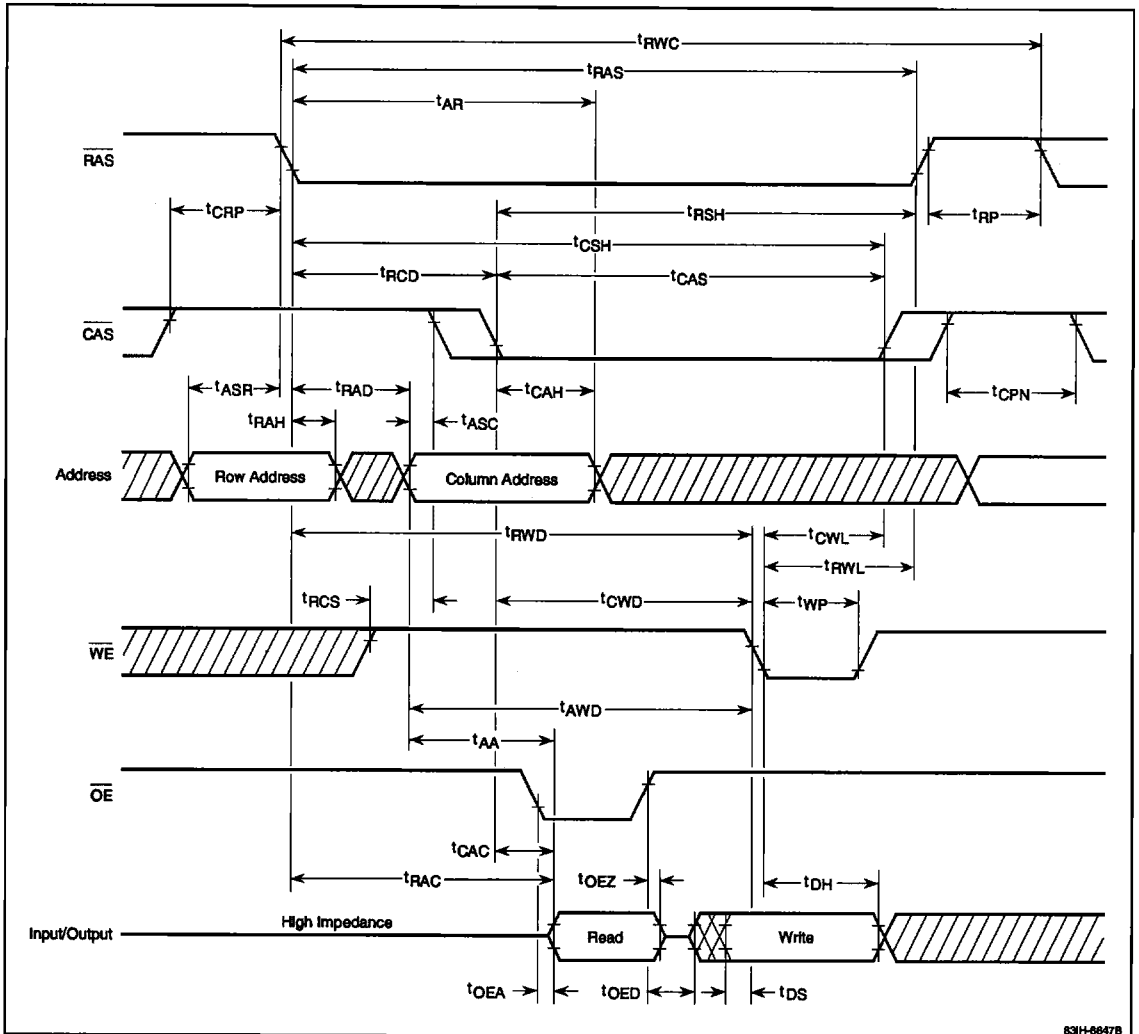
### $\overline{OE}$ -Controlled Write Cycle



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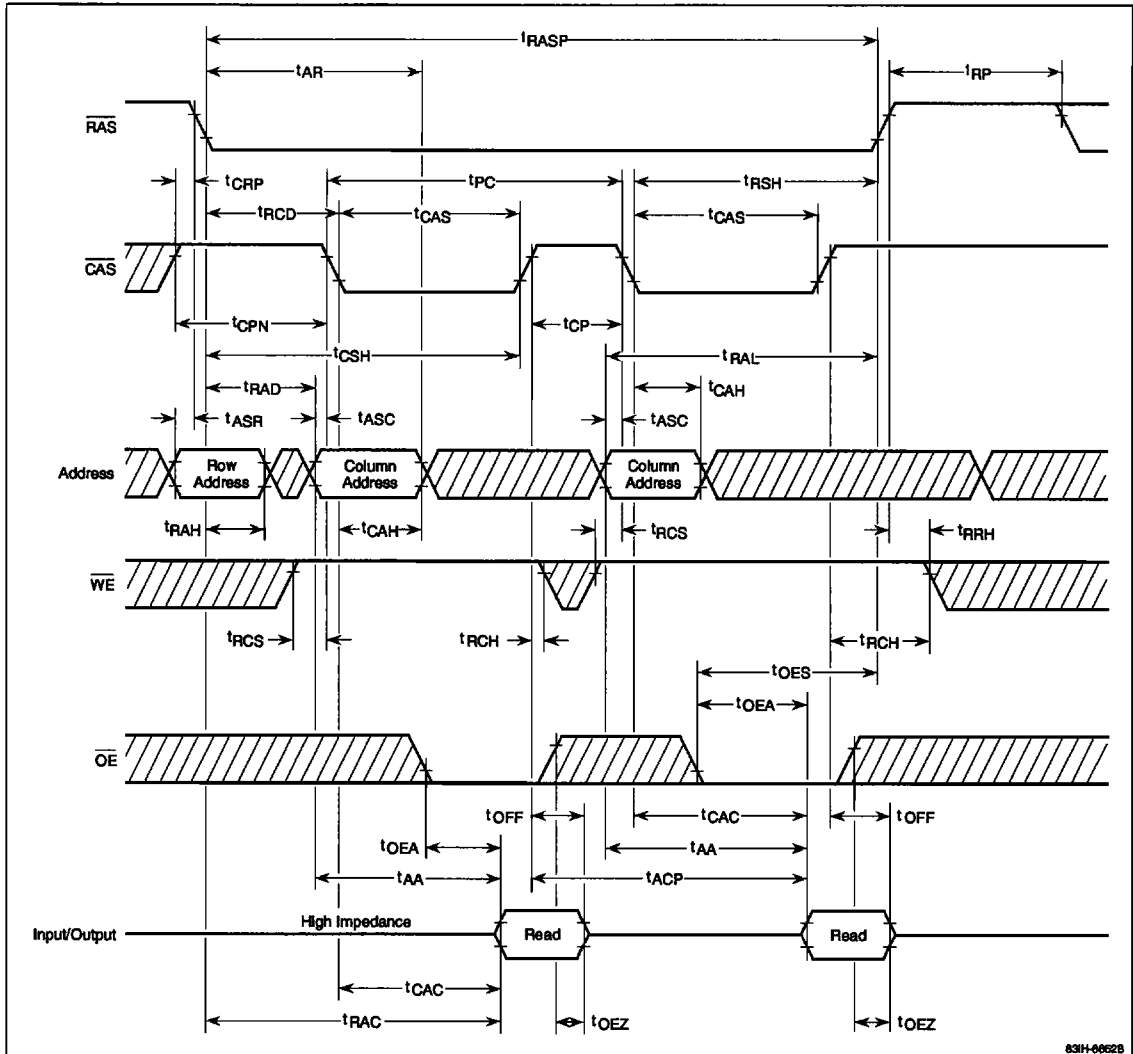
Timing Waveforms (cont)

Read-Write/Read-Modify-Write Cycle



## Timing Waveforms (cont)

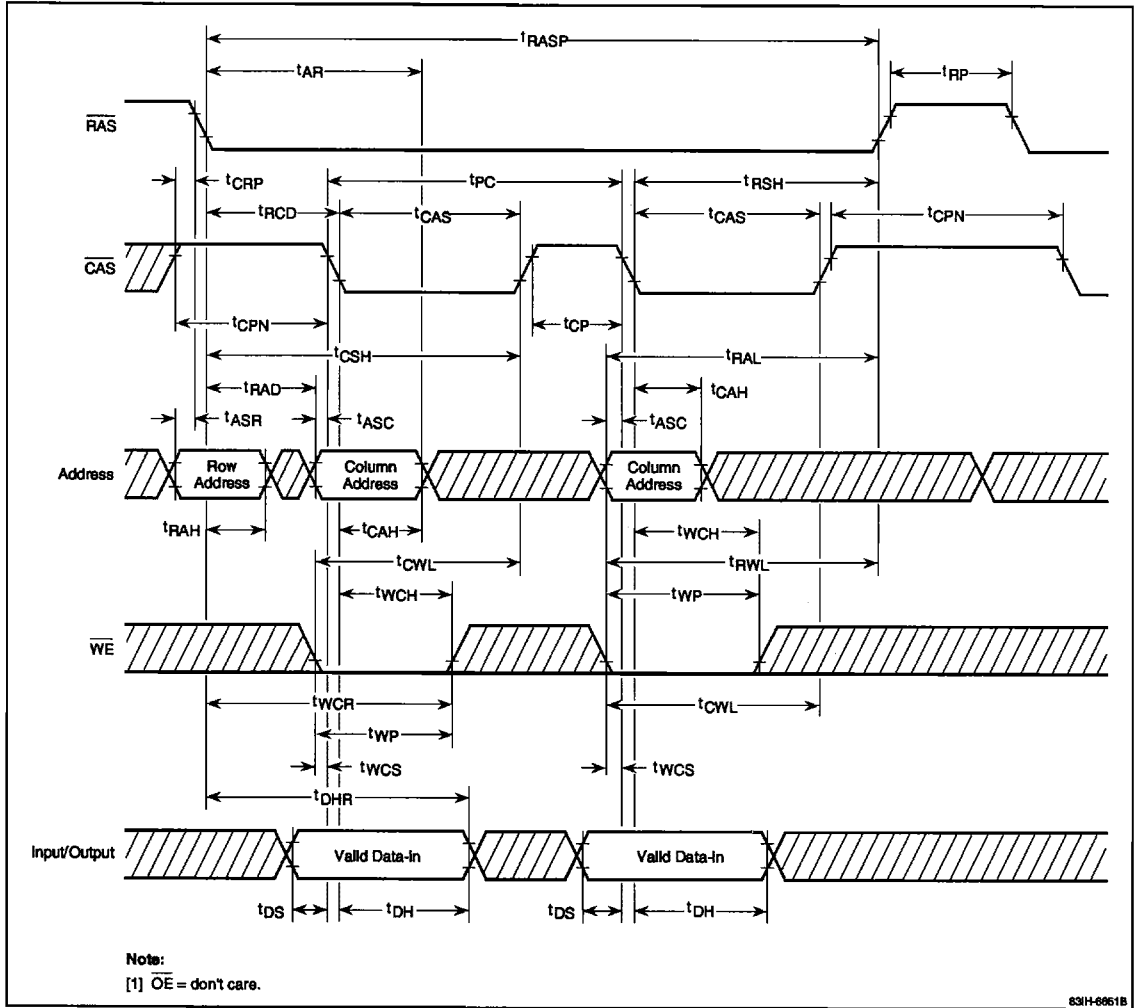
### Fast-Page Read Cycle



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Timing Waveforms (cont)

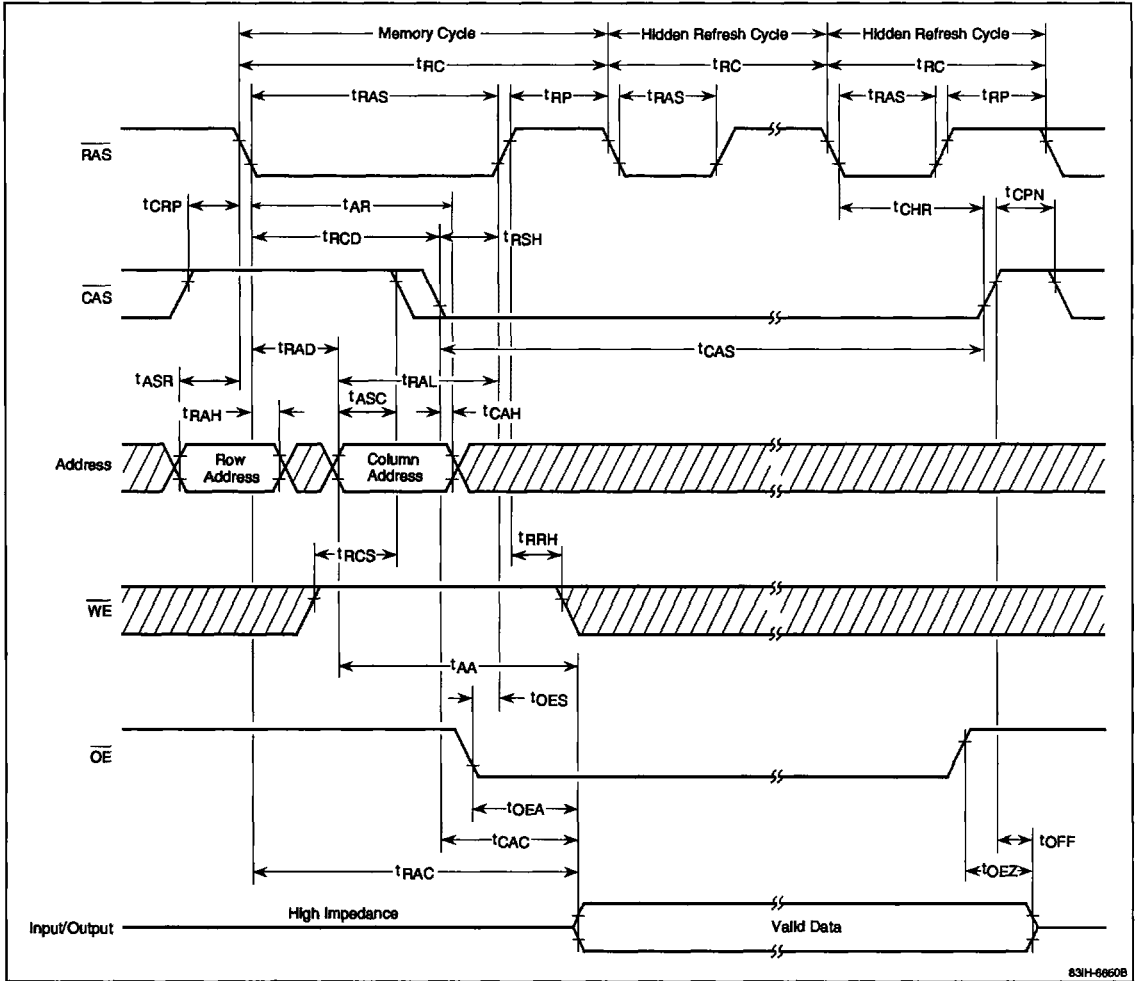
Fast-Page Early Write Cycle





Timing Waveforms (cont)

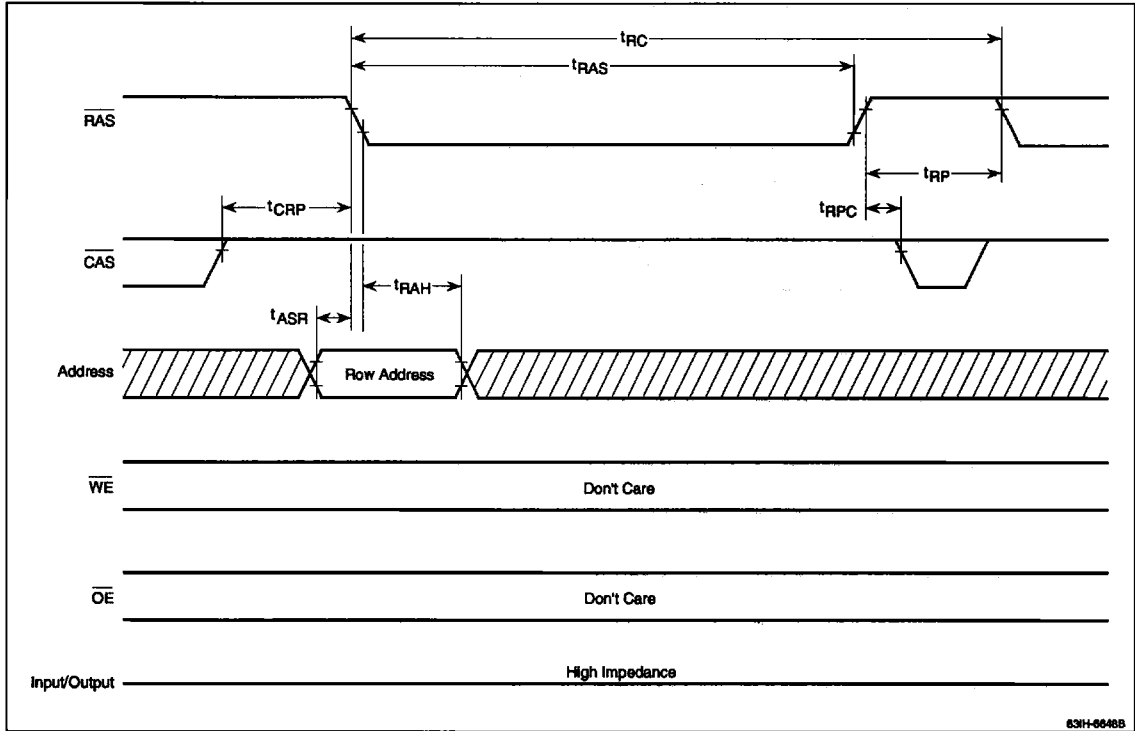
Hidden Refresh Cycle





## Timing Waveforms (cont)

### RAS-Only Refresh Cycle



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Timing Waveforms (cont)

*CAS Before RAS Refresh Cycle*

